





Cryogenic and hermetically sealed packaging of photonic chips for optomechanics: supplement

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1. TECHNICAL DRAWINGS

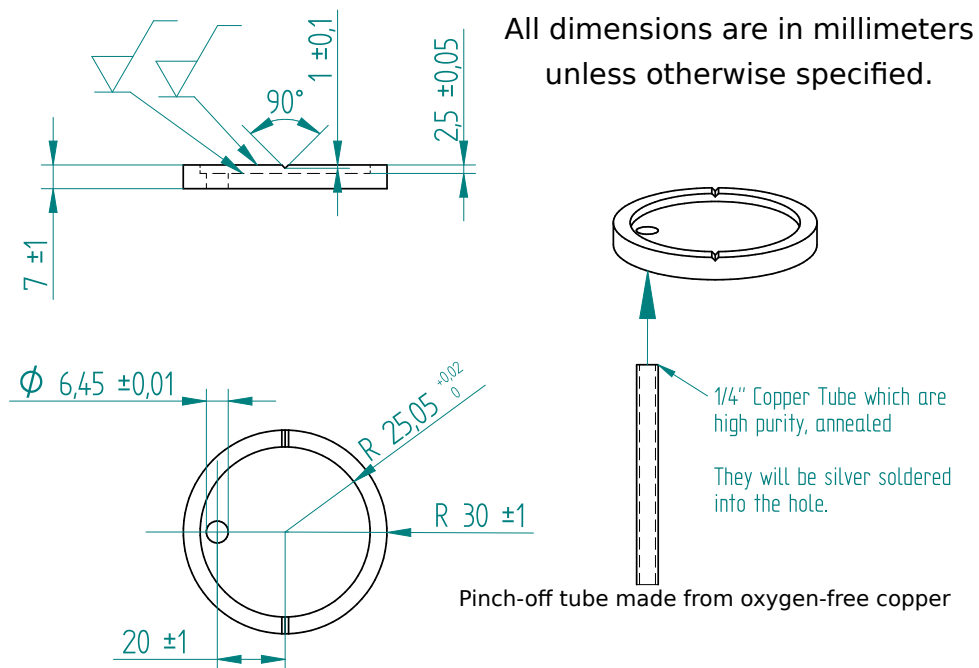


Fig. S1. Technical drawing of the top of a puck, containing dimensions used in some modern versions of the design. This side will be downwards facing if using the length of the pinch-off tube to control superfluid film thickness. Stycast epoxy (2850FT) gets applied in a thin layer around the extended edge and filling the v-shaped grooves before the top and base of the puck are pressed together.

Dimensions are in millimeters
unless otherwise marked

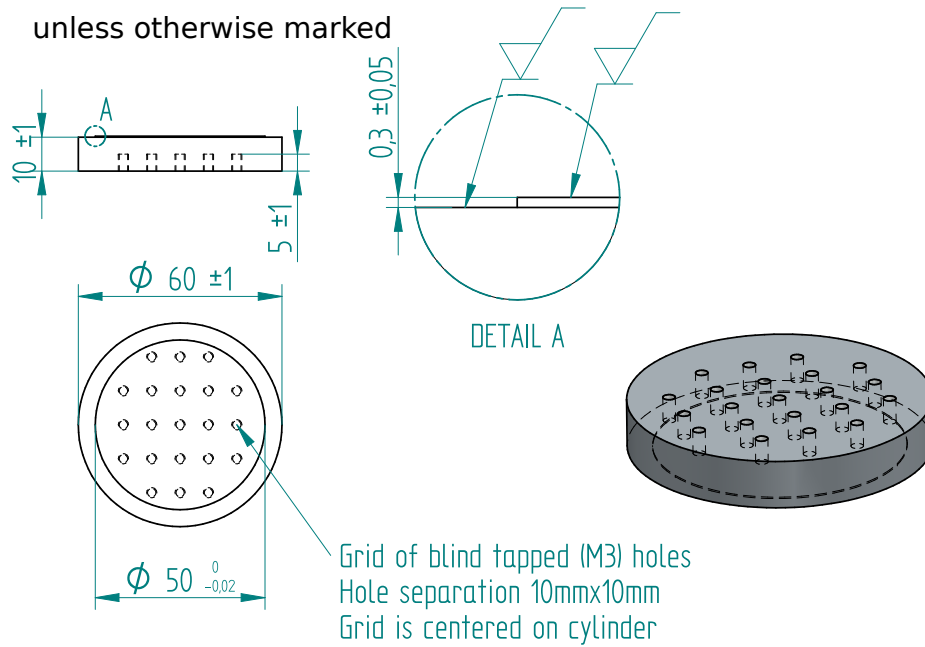


Fig. S2. Technical drawing of the base of a puck, containing dimensions used in some modern versions of the design. This side will be upwards facing if using the length of the pinch-off tube to control superfluid film thickness. Stycast epoxy (2850FT) gets applied in a thin layer around the recessed edge (and any optical fibers) before the top and base of the puck are pressed together.